

Docket No.: 50090-318

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Yoshifumi TAKATA, et al.

Serial No.: 09/903,760

Group Art Unit: 2822

Filed: July 13, 2001

Examiner: J. Mitchell

For: SEMICONDUCTOR DEVICE HAVING AN IMPROVED INTERLAYER  
CONDUCTOR CONNECTIONS AND A MANUFACTURING METHOD  
THEREOF

**AMENDMENT**

Commissioner for Patents  
Washington, DC 20231

Sir:

The following Amendment and Remarks are submitted in response to the Office  
Action dated October 16, 2002.

**IN THE CLAIMS:**

Please amend claim 9 as follows.

9. (Twice Amended) A method of manufacturing a semiconductor device  
comprising the steps of sequentially:

forming a first interlayer insulating film on a semiconductor substrate;

forming a plurality of openings in said first interlayer insulating film;

forming a conductor film on said first interlayer insulating film so as to fill said  
openings;

